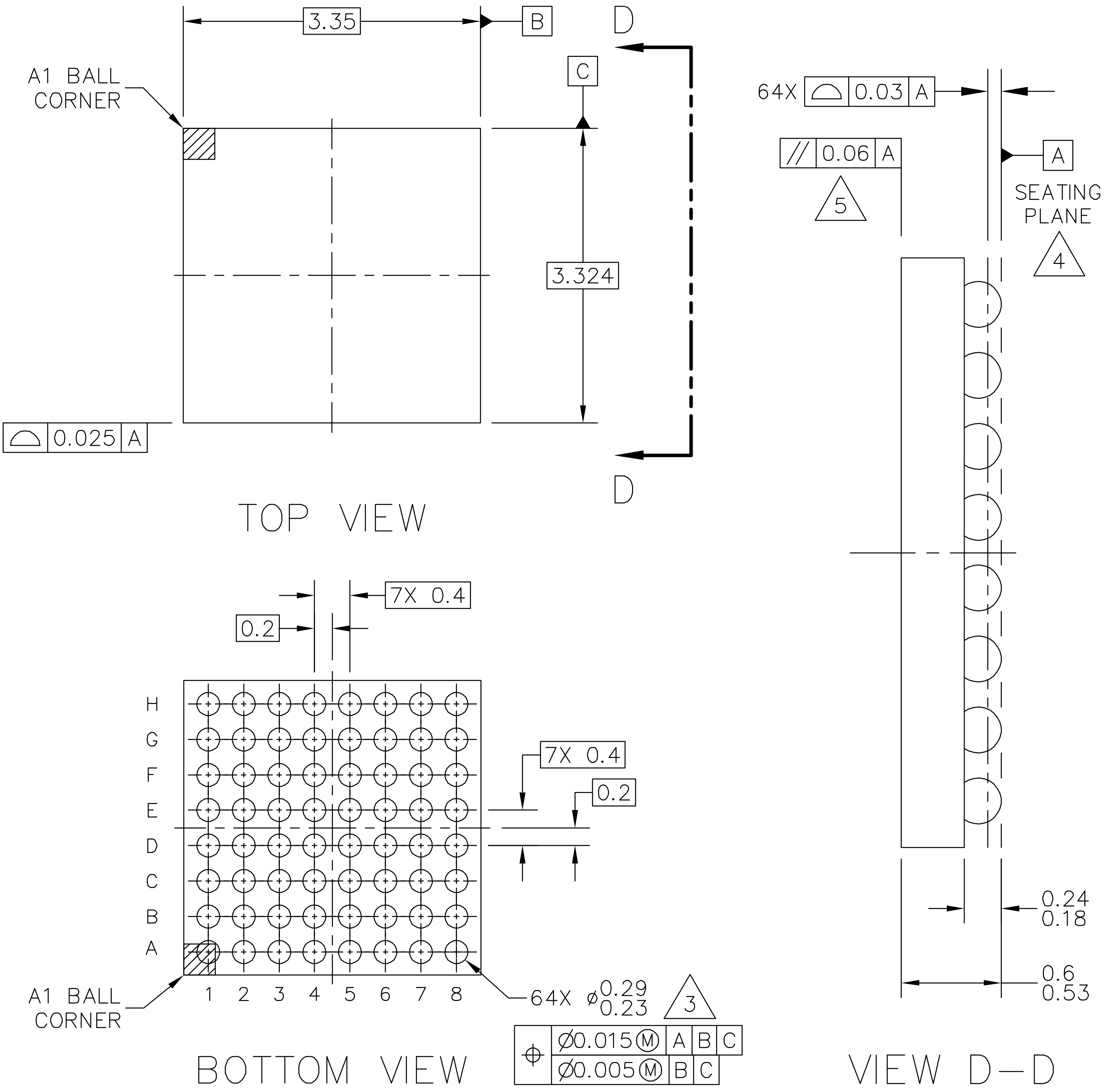

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TITLE: WLCSP, 3.35 X 3.324 X 0.565 PKG, 0.4 MM PITCH, 64 I/O	DOCUMENT NO: 98ASA00650D REV: A	
	STANDARD: NON—JEDEC	
	SOT1782—1 13 JAN 2016	

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5—2009.

△3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

△4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

△5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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